## N-Channel MOSFET

Power MOS 8™ is a high speed, high voltage N-channel switch-mode power MOSFET. A proprietary planar stripe design yields excellent reliability and manufacturability. Low switching loss is achieved with low input capacitance and ultra low C_{rss} "Miller" capacitance. The intrinsic gate resistance and capacitance of the poly-silicon gate structure help control slew rates during switching, resulting in low EMI and reliable paralleling, even when switching at very high frequency. Reliability in flyback, boost, forward, and other circuits is enhanced by the high avalanche energy capability.

SOT-227

UL® "UL Recognized" file # E145592

ISOTOP®
APT80M60J

Single die MOSFET
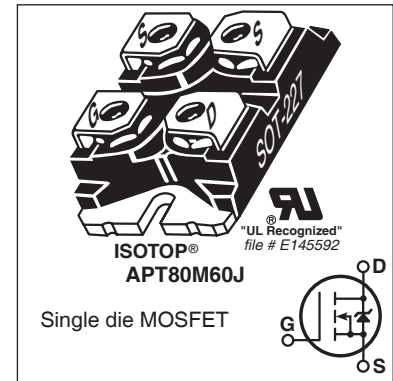
FEATURES

- **Fast switching with low EMI/RFI**
- **Low $R_{DS(on)}$**
- **Ultra low C_{rss} for improved noise immunity**
- **Low gate charge**
- **Avalanche energy rated**
- **RoHS compliant**

TYPICAL APPLICATIONS

- **PFC and other boost converter**
- **Buck converter**
- **Two switch forward (asymmetrical bridge)**
- **Single switch forward**
- **Flyback**
- **Inverters**

Absolute Maximum Ratings

Symbol	Parameter	Ratings	Unit
I_D	Continuous Drain Current @ T_C = 25°C	80	A
	Continuous Drain Current @ T_C = 100°C	50	
I_{DM}	Pulsed Drain Current ①	445	
V_{GS}	Gate-Source Voltage	±30	V
E_{AS}	Single Pulse Avalanche Energy ②	3350	mJ
I_{AR}	Avalanche Current, Repetitive or Non-Repetitive	60	A

Thermal and Mechanical Characteristics

Symbol	Characteristic	Min	Typ	Max	Unit
P_D	Total Power Dissipation @ T_C = 25°C			960	W
$R_{\theta JC}$	Junction to Case Thermal Resistance			0.13	°C/W
$R_{\theta CS}$	Case to Sink Thermal Resistance, Flat, Greased Surface		0.15		
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55		150	°C
$V_{Isolation}$	RMS Voltage (50-60hHz Sinusoidal Waveform from Terminals to Mounting Base for 1 Min.)	2500			V
W_T	Package Weight		1.03		oz
			29.2		g
Torque	Terminals and Mounting Screws.			10	in·lbf
				1.1	N·m

Static Characteristics

Symbol	Parameter	Test Conditions		Min	Typ	Max	Unit
$V_{BR(DSS)}$	Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = 250µA		600			V
$\Delta V_{BR(DSS)}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I_D = 250µA			0.57		V/°C
$R_{DS(on)}$	Drain-Source On Resistance [3]	V_{GS} = 10V, I_D = 60A			0.047	0.060	Ω
$V_{GS(th)}$	Gate-Source Threshold Voltage	V_{GS} = V_{DS}, I_D = 5mA		3	4	5	V
$\Delta V_{GS(th)}/\Delta T_J$	Threshold Voltage Temperature Coefficient				-10		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 600V V_{GS} = 0V	T_J = 25°C			100	µA
			T_J = 125°C			500	
I_{GSS}	Gate-Source Leakage Current	V_{GS} = ±30V				±100	nA

Dynamic Characteristics T_J = 25°C unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
g_{fs}	Forward Transconductance	V_{DS} = 50V, I_D = 60A		115		S
C_{iss}	Input Capacitance	V_{GS} = 0V, V_{DS} = 25V f = 1MHz		24000		pF
C_{rss}	Reverse Transfer Capacitance			245		
C_{oss}	Output Capacitance			2200		
$C_{o(cr)}$ [4]	Effective Output Capacitance, Charge Related	V_{GS} = 0V, V_{DS} = 0V to 400V		1170		
$C_{o(er)}$ [5]	Effective Output Capacitance, Energy Related			605		
Q_g	Total Gate Charge	V_{GS} = 0 to 10V, I_D = 60A, V_{DS} = 300V		600		nC
Q_{gs}	Gate-Source Charge			130		
Q_{gd}	Gate-Drain Charge			250		
$t_{d(on)}$	Turn-On Delay Time	**Resistive Switching** V_{DD} = 400V, I_D = 60A R_G = 2.2Ω [6], V_{GG} = 15V		135		ns
t_r	Current Rise Time			155		
$t_{d(off)}$	Turn-Off Delay Time			410		
t_f	Current Fall Time			125		

Source-Drain Diode Characteristics

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
I_S	Continuous Source Current (Body Diode)	MOSFET symbol showing the integral reverse p-n junction diode (body diode)			80	A
I_{SM}	Pulsed Source Current (Body Diode) [1]				445	
V_{SD}	Diode Forward Voltage	I_{SD} = 60A, T_J = 25°C, V_{GS} = 0V			1.0	V
t_{rr}	Reverse Recovery Time	I_{SD} = 60A [3]		900		ns
Q_{rr}	Reverse Recovery Charge	di_{SD}/dt = 100A/µs, T_J = 25°C		37		µC
dv/dt	Peak Recovery dv/dt	$I_{SD} \leq$ 60A, di/dt $\leq$1000A/µs, V_{DD} = 100V, T_J = 125°C			8	V/ns

[1] Repetitive Rating: Pulse width and case temperature limited by maximum junction temperature.

[2] Starting at T_J = 25°C, L = 1.86mH, R_G = 2.2Ω, I_{AS} = 60A.

[3] Pulse test: Pulse Width < 380µs, duty cycle < 2%.

[4] $C_{o(cr)}$ is defined as a fixed capacitance with the same stored charge as C_{OSS} with V_{DS} = 67% of $V_{(BR)DSS}$.

[5] $C_{o(er)}$ is defined as a fixed capacitance with the same stored energy as C_{OSS} with V_{DS} = 67% of $V_{(BR)DSS}$. To calculate $C_{o(er)}$ for any value of V_{DS} less than $V_{(BR)DSS}$, use this equation: $C_{o(er)}$ = -2.32E-7/V_{DS}^2 + 9.75E-8/V_{DS} + 3.64E-10.

[6] R_G is external gate resistance, not including internal gate resistance or gate driver impedance. (MIC4452)

Microsemi reserves the right to change, without notice, the specifications and information contained herein.
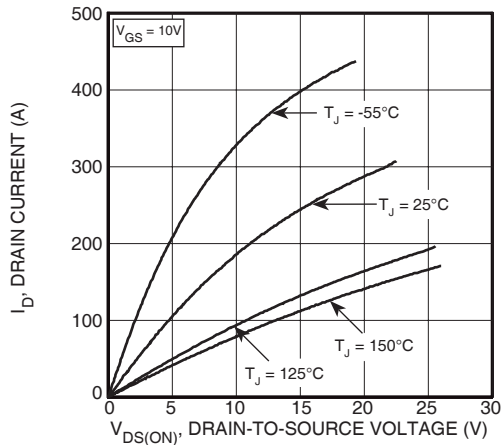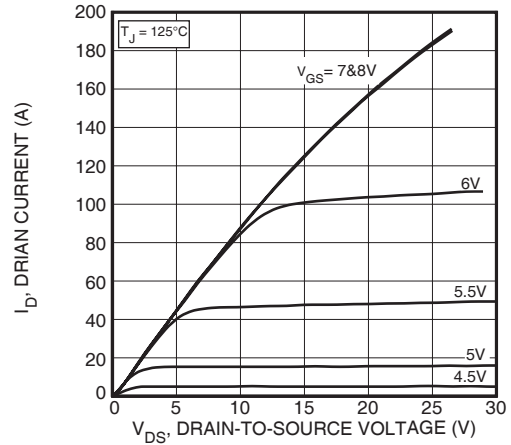
Figure 1, Output Characteristics
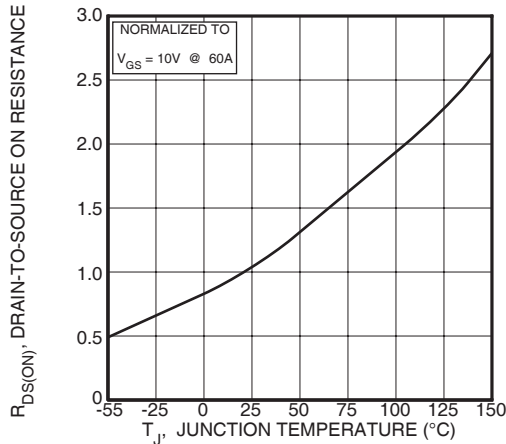

Figure 2, Output Characteristics

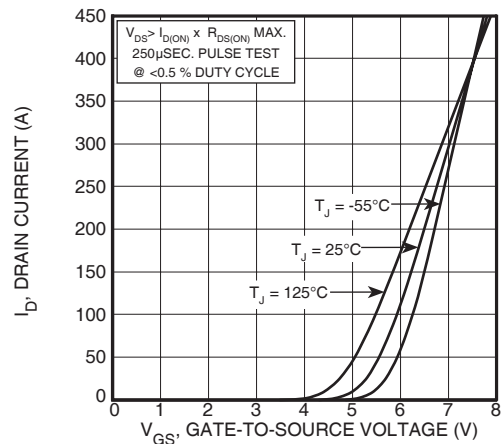**Figure 3, $R_{DS(ON)}$ vs Junction Temperature**

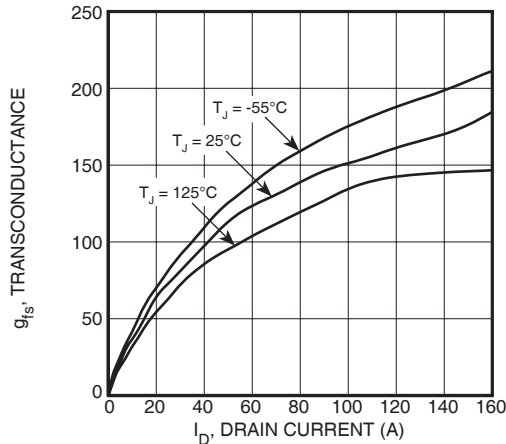**Figure 4, Transfer Characteristics**

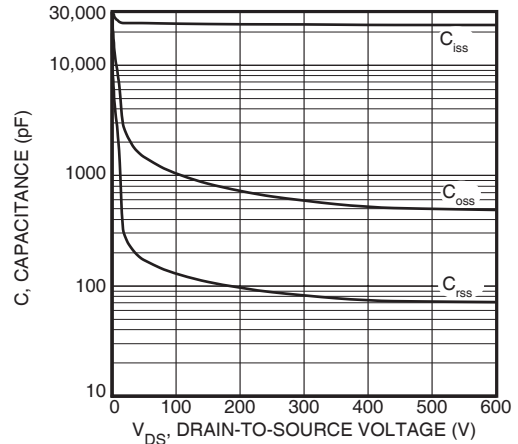

Figure 5, Gain vs Drain Current

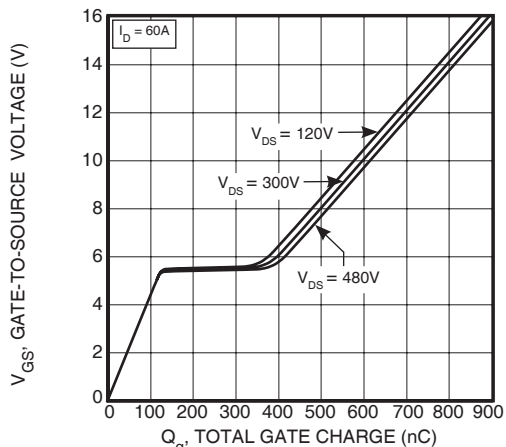**Figure 6, Capacitance vs Drain-to-Source Voltage**
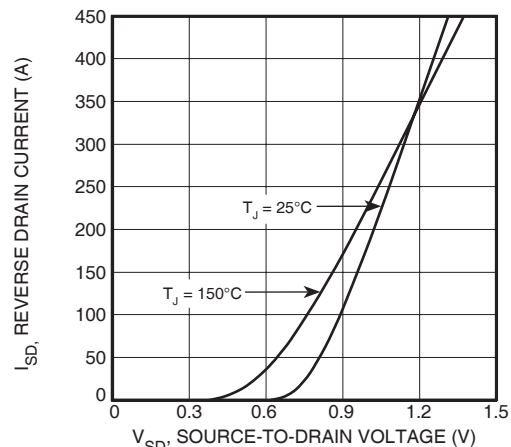

Figure 7, Gate Charge vs Gate-to-Source Voltage

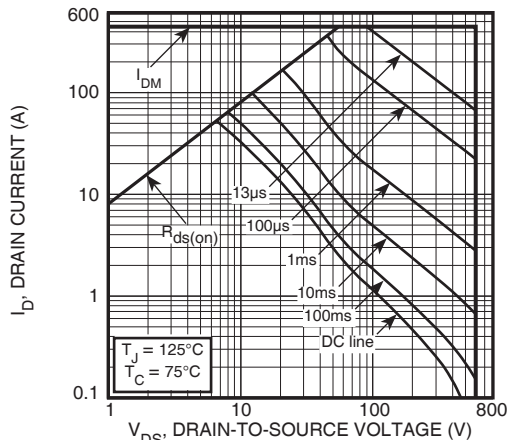

Figure 8, Reverse Drain Current vs Source-to-Drain Voltage
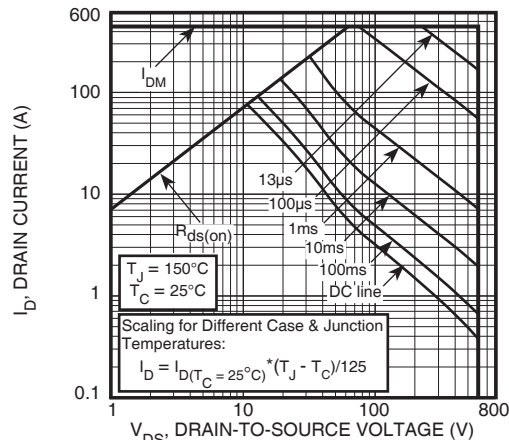
Figure 9, Forward Safe Operating Area
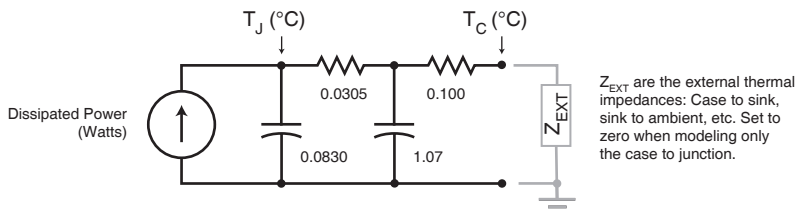

Figure 10, Maximum Forward Safe Operating Area

Figure 11, Transient Thermal Impedance Model

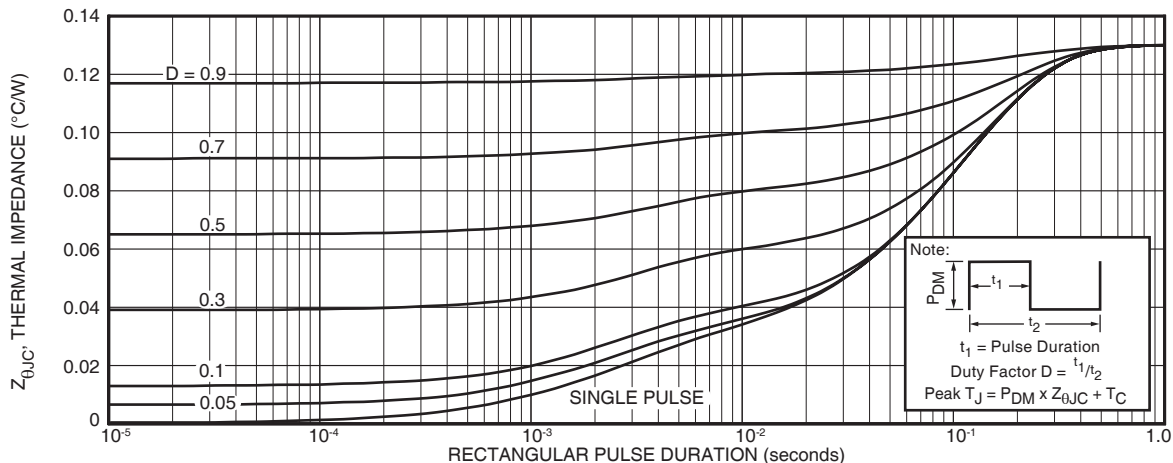Z_{EXT} are the external thermal impedances: Case to sink, sink to ambient, etc. Set to zero when modeling only the case to junction.

t_1 = Pulse Duration
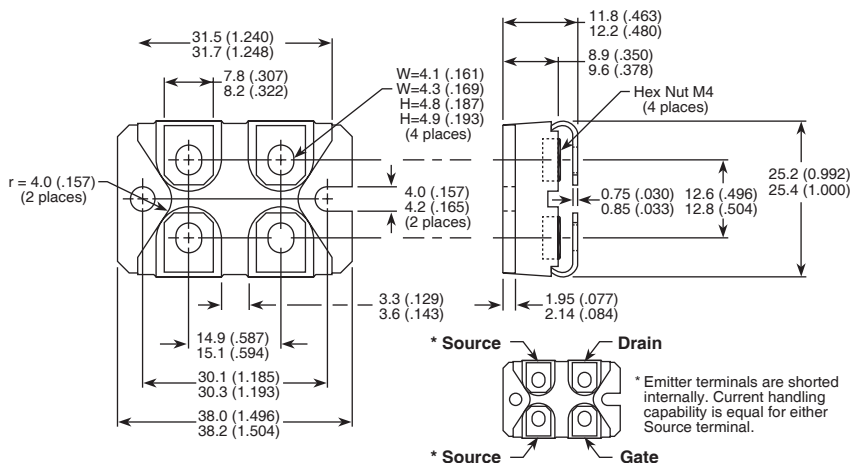Duty Factor D = t_1/t_2
Peak $T_J = P_{DM} \times Z_{\theta JC} + T_C$

Figure 12. Maximum Effective Transient Thermal Impedance Junction-to-Case vs Pulse Duration

SOT-227 (ISOTOP®) Package Outline

* Emitter terminals are shorted internally. Current handling capability is equal for either Source terminal.

Dimensions in Millimeters and (Inches)